



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-21
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HYE3*V802ALL	A	ZS1A	2015-07-21
Amount	UoM	Unit type	ST ECOPACK Grade	
23.70	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	3 - 3 - 0.86	8	J bend	
Comment	Package: E3 MSOP/TSSOP 8 BODY3.00 PITCH0.65; MDF valid for LMV358LIST			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HYE3*V80ZALL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.436	mg	supplier	die	Silicon (Si)	7440-21-3		0.417	mg	956422	17595
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	11468	211
Silicon Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	2294	42
Silicon Die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.001	mg	2294	42
Silicon Die				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.012	mg	27523	506
Lead-frame	Copper & its alloys	9.19	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.808	mg	958433	371646
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.253	mg	27530	10675
Lead-frame				supplier	alloy	Phosphorus (P)	12185-10-3		0.002	mg	218	84
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.015	mg	1632	633
Lead-frame				supplier	metallization	Silver (Ag)	7440-22-4		0.112	mg	12187	4726
Die attach	Other inorganic materials	0.235	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.162	mg	689362	6835
Die attach				supplier	glue or tape	methylene diacrylate	42594-17-2		0.059	mg	251064	2489
Die attach				supplier	glue or tape	Dicyclopentenylmethoxyethyl methacrylate	68586-19-6		0.007	mg	29787	295
Die attach				supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.007	mg	29787	295
Bonding wire	Precious metals	0.175	mg	supplier	wire	Gold (Au)	7440-57-5		0.175	mg	1000000	7384
Encapsulation	Other inorganic materials	12.887	mg	supplier	molding compound	Silica, vitreous	60676-86-0		10.683	mg	828975	450759
Encapsulation				supplier	molding compound	phenolic resin	Proprietary		0.524	mg	40661	22110
Encapsulation				supplier	molding compound	epoxy resin	Proprietary		0.6	mg	46559	25316
Encapsulation				supplier	molding compound	Biphenyl epoxy resin	29690-82-2		0.299	mg	23202	12616
Encapsulation				supplier	molding compound	carbon black	25068-38-6		0.03	mg	2328	1266
Encapsulation				supplier	molding compound	Zinc hydroxide	20427-58-1		0.151	mg	11717	6371
Encapsulation				supplier	molding compound	Magnesium hydroxide	1309-42-8		0.6	mg	46559	25316
connections coating	Solder	0.775	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.775	mg	1000000	32700